

Low Profile 4G LTE SMD Dielectric Antenna

7AS CARA

Part No: PCS.26.A

Description:

Features:

High Efficiency 4G LTE SMD antenna Covers 600-3000MHz Band 71 Ready Dimensions: 54.6*13*3mm RoHS & Reach Compliant



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1. Introduction



The PCS.26.A is a low-profile SMD 4G/LTE embedded antenna designed for direct SMD mount on a device PCB. It provides high efficiency in a very small form factor, at 54.6*13*3mm. Its rectangular shape and very small size make it very easy to integrate. Packaged in tape and reel, it can be mounted via pick and place to reflow solder directly on the edge of the PCB board.

The antenna is a great match for lower cost cellular applications, particularly in the telematics and automotive sector, but also for for IoT applications as it exhibits outstanding performance on variable ground plane lengths – meaning it can be used in small devices.

Typical Applications Include:

- IoT Sensors and devices
- Connected Health
- Wearables

This antenna is recommended for use with longer ground-plane lengths of 100mm or more for maximum efficiency. Some tuning can be performed on this antenna to help optimize to the device environment. Contact your regional Taoglas customer support team for further information.



2. Specifications

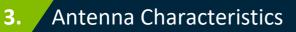
			Elect	rical				
Frequency (MHz)	617-698	698-806	824-894	880-960	1710- 1880	1850- 1990	1920- 2170	2300- 2690
Peak Gain (dBi)	2.36	3.66	3.99	3.82	6.44	6.44	5.95	4.85
Average Gain (dB)	-1.85	-1.35	-1.14	-1.35	-1.22	-1.15	-1.49	-1.68
Efficiency (%)	65.9	73.3	76.9	73.4	75.6	76.8	70.9	68.5
Return Loss (dB)		<-7			<-	-7		<-6
Polarization				Lin	ear			
Impedance				50	Ω			
Maximum Input Power				51	N			
			Mech	anical				
Antenna Dimensi	ions			54.6m	m x 13mm x	3mm		
Material					FR4			
Soldering Type	e			SMD	through Re	flow		
			Environ	mental				
Operation Tempera	ature			-	40°C ~ +85°(0		
Storage Temperat	ture			-	40°C ~ +85°(C		
Moisture Sensitivity Le	vel (MSL)			3	8 (168 Hours)		

* All measurements were SMD on 178*55.6mm EVB board

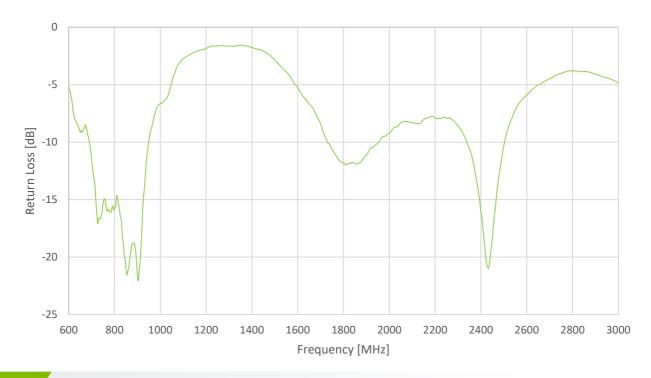


		5G/4G Bands	
Band Number	5GNR / FR1 / LT	E / LTE-Advanced / WCDMA / HSPA / HSI	PA+ / TD-SCDMA
	Uplink	Downlink	Covered
1	UL: 1920 to 1980	DL: 2110 to 2170	\checkmark
2	UL: 1850 to 1910	DL: 1930 to 1990	\checkmark
3	UL: 1710 to 1785	DL: 1805 to 1880	\checkmark
4	UL: 1710 to 1755	DL: 2110 to 2155	\checkmark
5	UL: 824 to 849	DL: 869 to 894	\checkmark
7	UL: 2500 to 2570	DL:2620 to 2690	\checkmark
8	UL: 880 to 915	DL: 925 to 960	\checkmark
9	UL: 1749.9 to 1784.9	DL: 1844.9 to 1879.9	\checkmark
11	UL: 1427.9 to 1447.9	DL: 1475.9 to 1495.9	*
12	UL: 699 to 716	DL: 729 to 746	\checkmark
13	UL: 777 to 787	DL: 746 to 756	\checkmark
14	UL: 788 to 798	DL: 758 to 768	\checkmark
17	UL: 704 to 716	DL: 734 to 746	\checkmark
18	UL: 815 to 830	DL: 860 to 875	\checkmark
19	UL: 830 to 845	DL: 875 to 890	\checkmark
20	UL: 832 to 862	DL: 791 to 821	\checkmark
21	UL: 1447.9 to 1462.9	DL: 1495.9 to 1510.9	*
22	UL: 3410 to 3490	DL: 3510 to 3590	*
23	UL:2000 to 2020	DL: 2180 to 2200	\checkmark
24	UL:1625.5 to 1660.5	DL: 1525 to 1559	\checkmark
25	UL: 1850 to 1915	DL: 1930 to 1995	\checkmark
26	UL: 814 to 849	DL: 859 to 894	\checkmark
27	UL: 807 to 824	DL: 852 to 869	\checkmark
28	UL: 703 to 748	DL: 758 to 803	✓
29	UL: -	DL: 717 to 728	\checkmark
30	UL: 2305 to 2315	DL: 2350 to 2360	\checkmark
31	UL: 452.5 to 457.5	DL: 462.5 to 467.5	*
32	UL: -	DL: 1452 - 1496	*
35		1850 to 1910	✓
38		2570 to 2620	✓
39		1880 to 1920	✓
40		2300 to 2400	√
41		2496 to 2690	\checkmark
42		3400 to 3600	×
43		3600 to 3800	×
48		3550 to 3700	*
66	UL: 1710-1780	DL:2110-2200	1
71		617 to 698	1
74/75/76		1427 to 1518	\checkmark
78		3300 to 3800	*
79		4400 to 5000	*
85	698-716	728-746	\checkmark



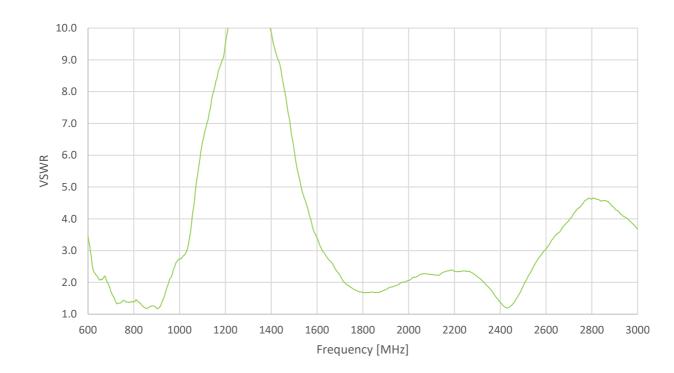




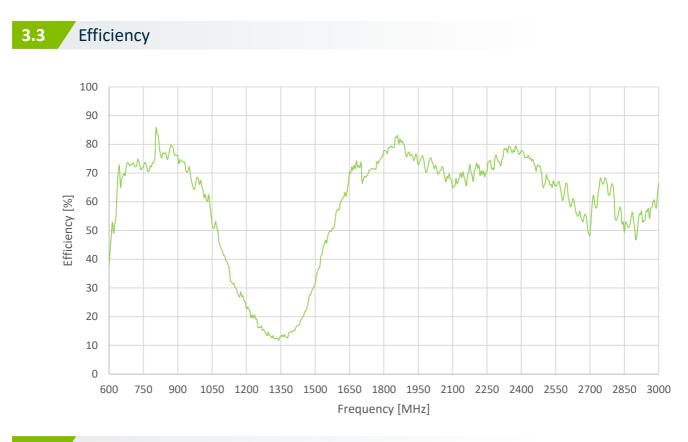




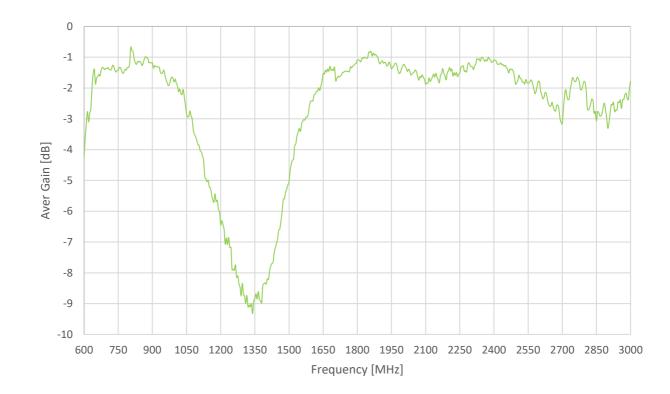
VSWR





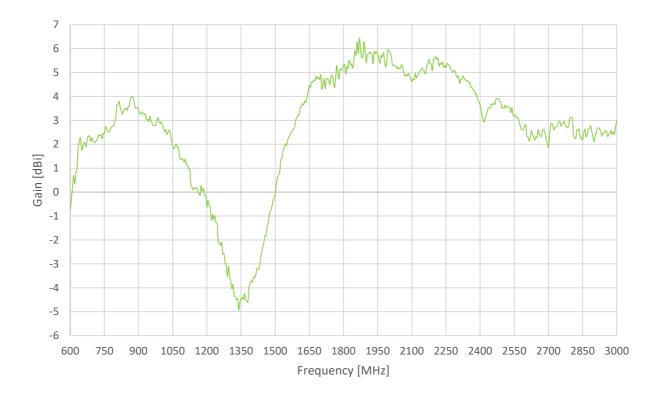






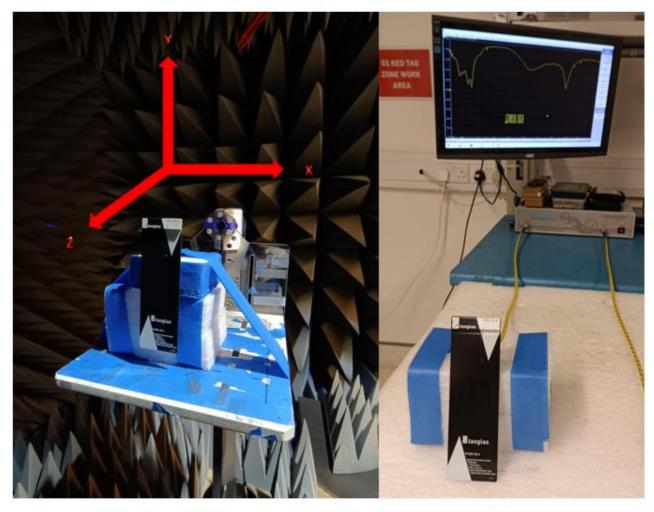


3.5 Peak Gain





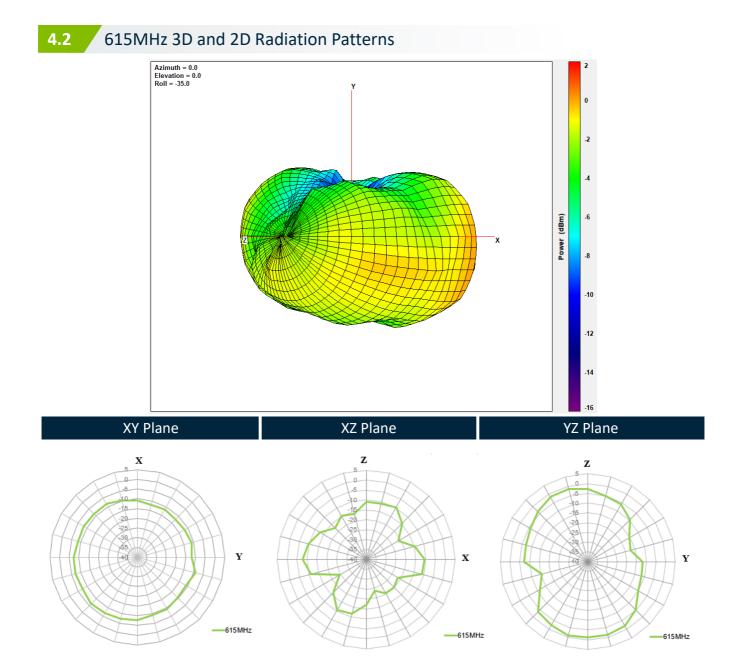
4.1 Test Setup



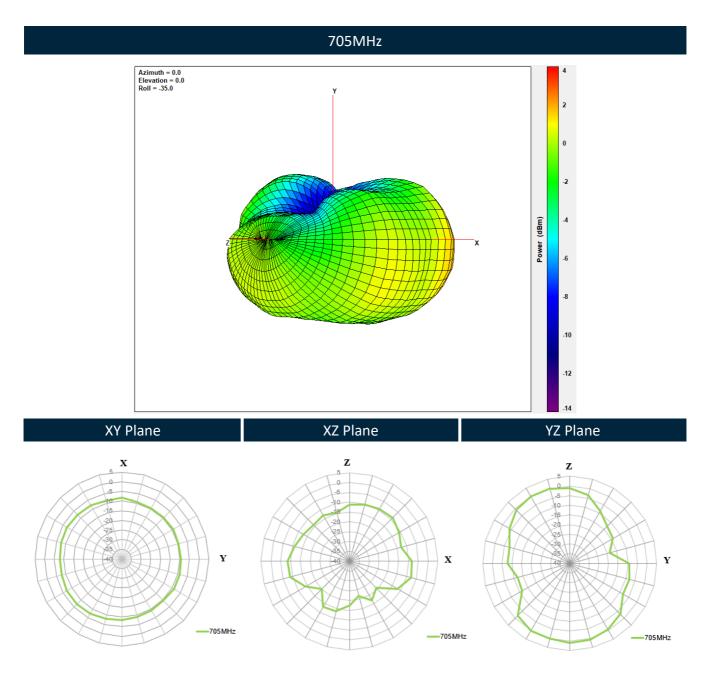
Chamber Setup

VNA Setup

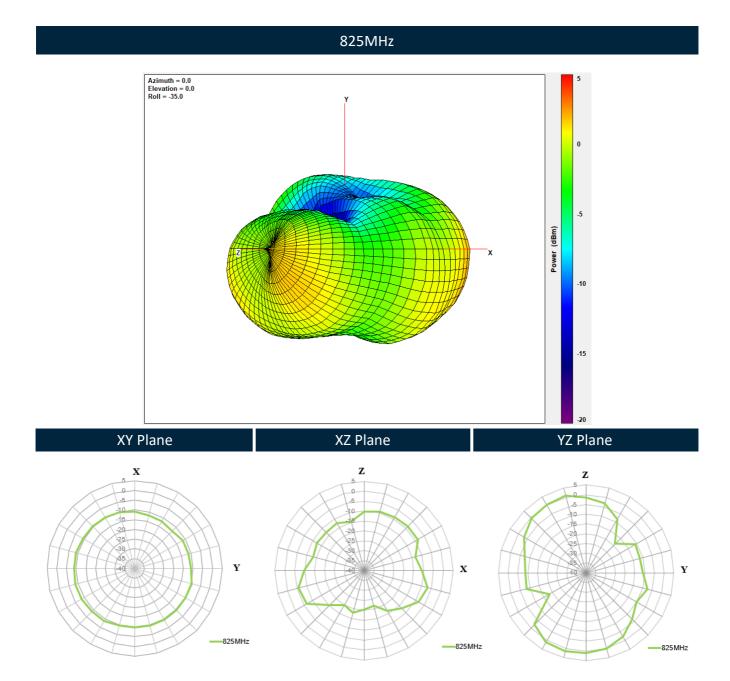




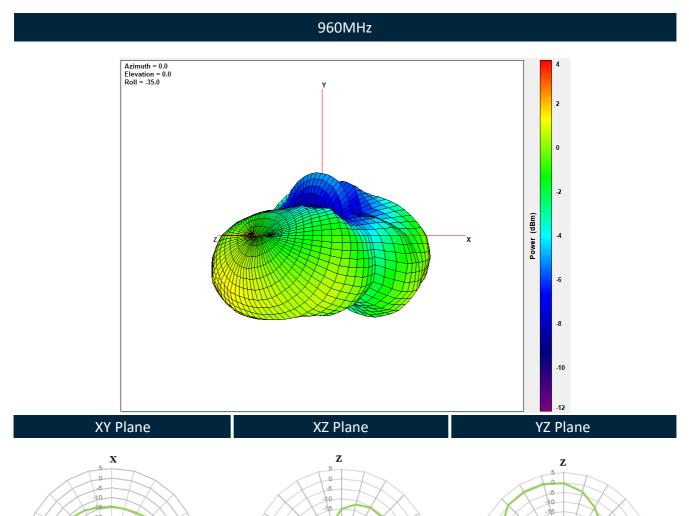


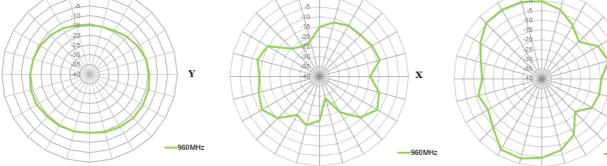










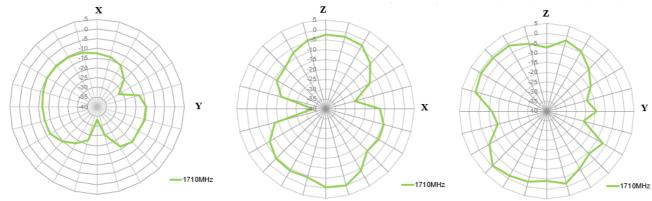


Y

960MHz

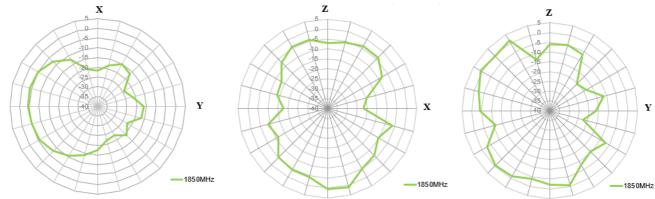


1710MHz Azimuth = 0.0 Elevation = 0.0 Roll = -35.0 6 4 2 0 -2 Power (dBm) -4 x -6 -8 -10 -12 -14 XZ Plane XY Plane YZ Plane

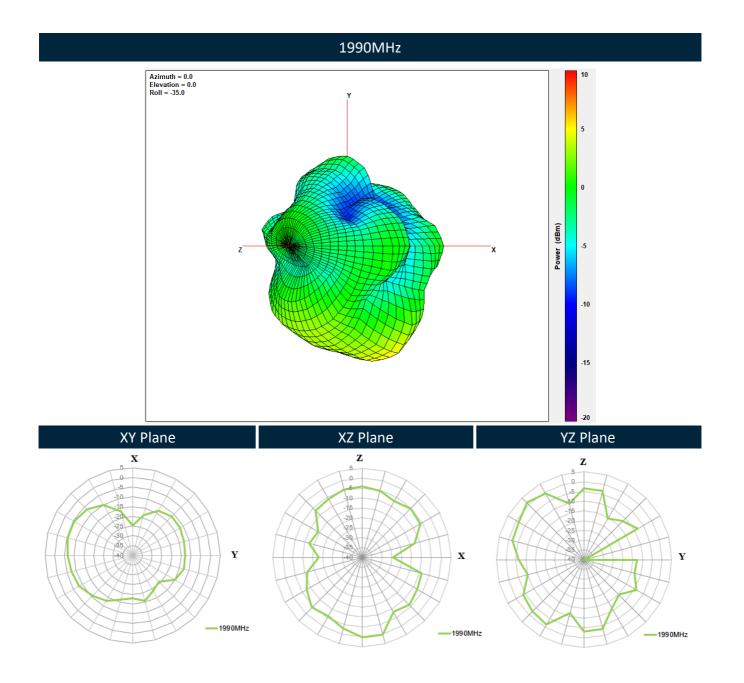




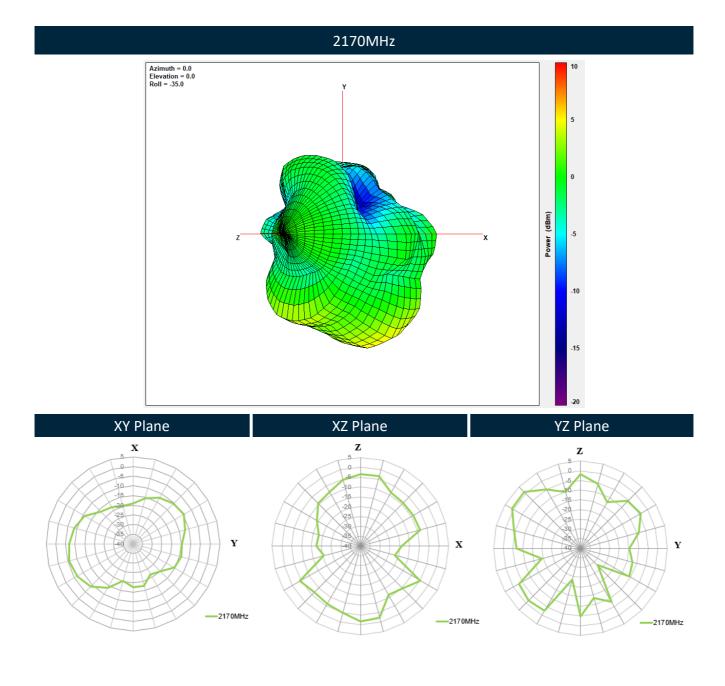
1850MHz Azimuth = 0.0 Elevation = 0.0 Roll = -35.0 4 2 0 -2 Power (dBm) .4 7 -6 -8 -10 -12 -14 XY Plane XZ Plane YZ Plane



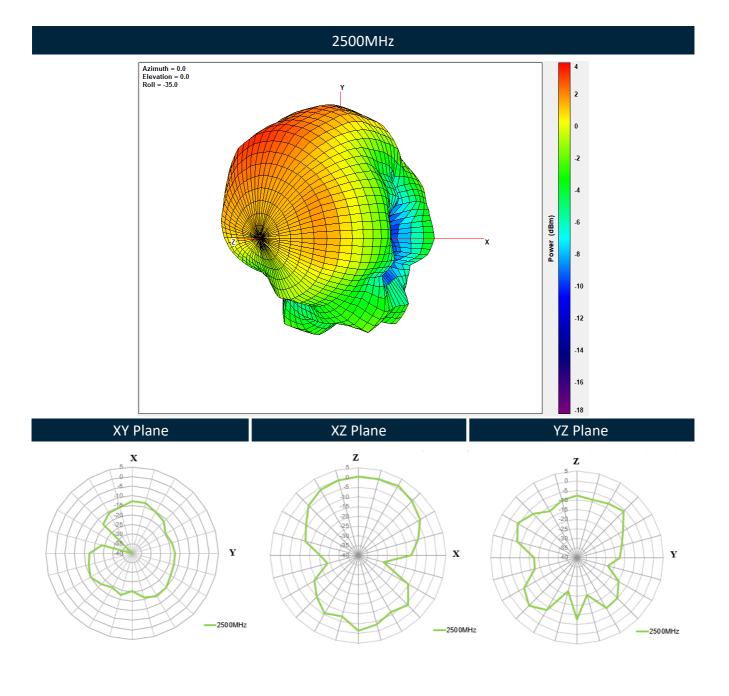




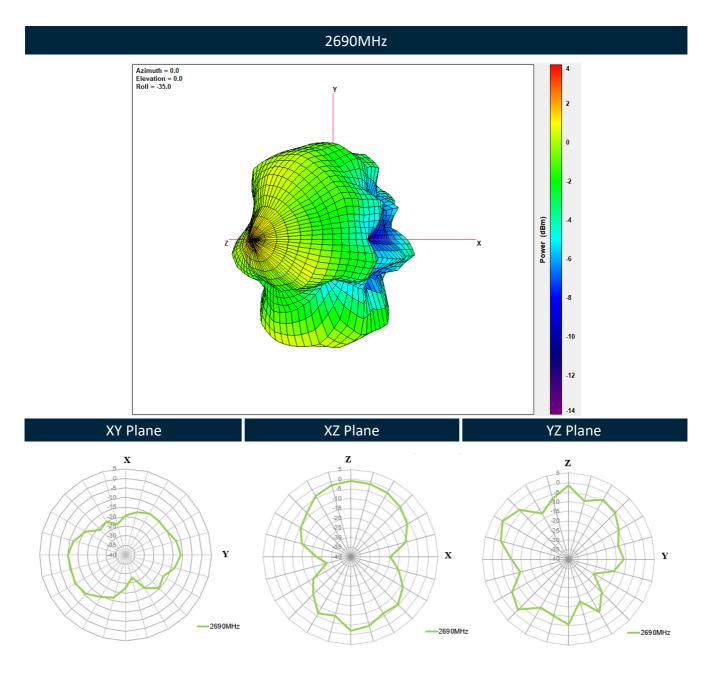




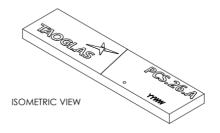


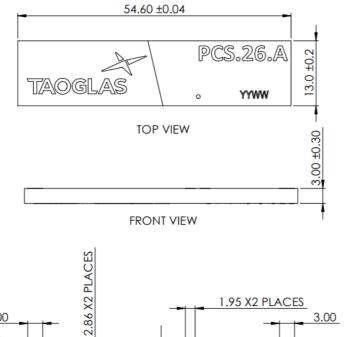


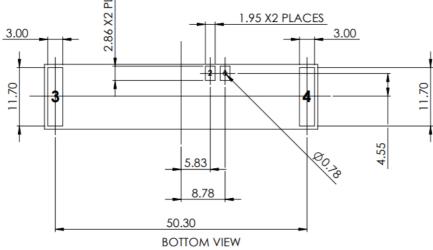














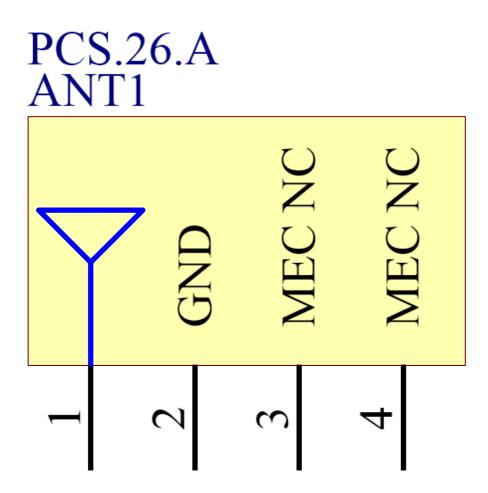




6.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 4 pins with only two pins (Pin 1 and Pin 2) as functional. Pins 3 and 4 are for mechanical strength.

Pin	Description
1	RF Feed
2	Ground
3, 4	Mechanical, Not Connected





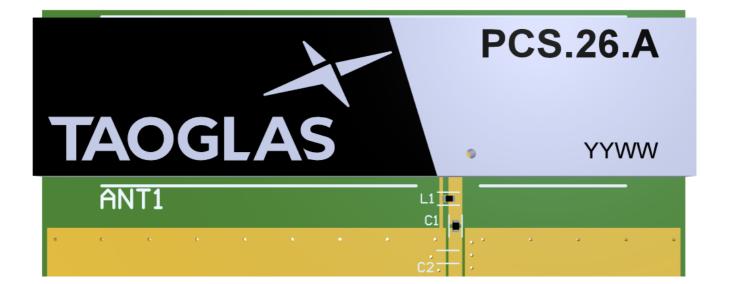
6.2 Antenna Integration

Whatever the size of the PCB, the antenna should ideally be placed on the PCB's shortest side, to take advantage of the ground plane. Optimized matching components can be placed as shown.



6.3 PCB Layout

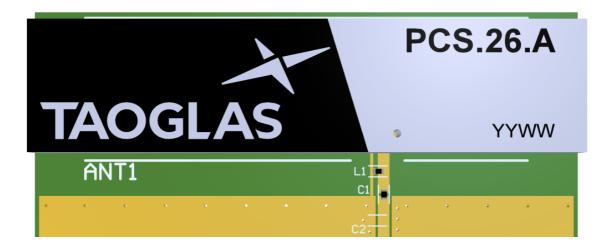
The footprint and clearance on the PCB must meet the antenna specification. An example of the PCB layout shows the antenna footprint with clearance. Note the placement of the optimized components. L1 is positioned outside the ground plane and C1 is sitting across the ground plane and the copper clearance area. C2 is optional as a component but it is recommended to include these pads in case they are needed.

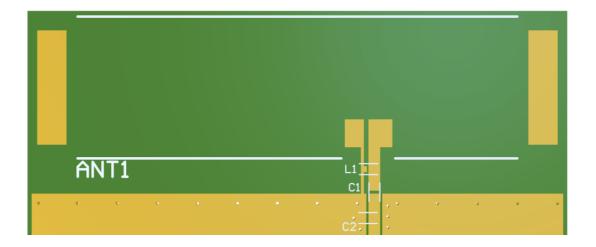




6.4 PCB Layout

The footprint and clearance on the PCB must meet the antenna specification. An example of the PCB layout shows the antenna footprint with clearance. Note the placement of the optimized components. L1 is positioned outside the ground plane and C1 is sitting across the ground plane and the copper clearance area. C2 is optional as a component but it is recommended to include these pads in case they are needed.

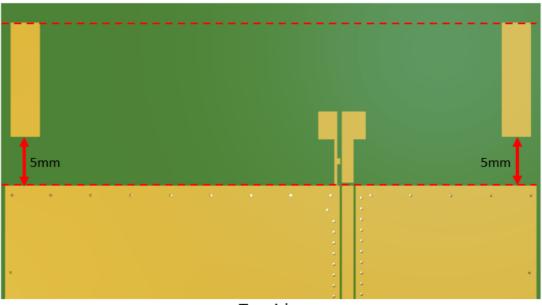




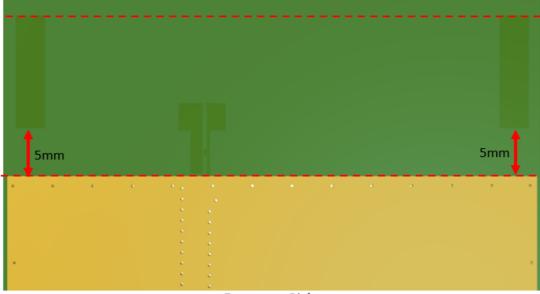


6.5 PCB Clearance

Below shows the antenna footprint and clearance through ALL layers on the PCB. Only the antenna pads and connections to feed and GND are present within this clearance area (marked RED). The clearance area extends to 5mm from the antenna mechanical pads to the ground area. This clearance area includes the bottom side and ALL internal layers on the PCB.



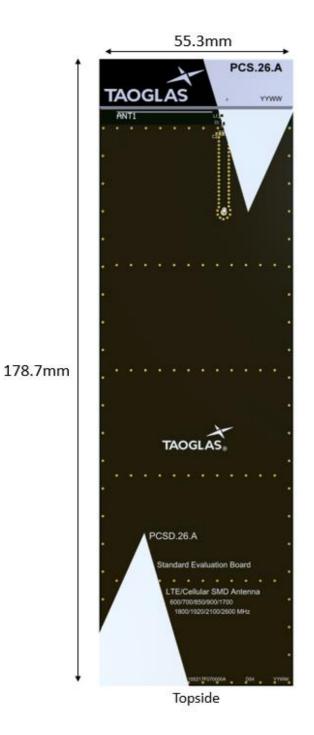
Topside

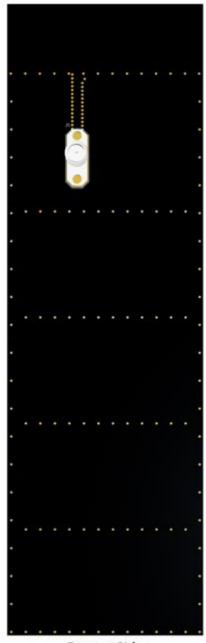


Bottom Side



6.6 Evaluation Board





Bottom Side



6.7 Evaluation Board Ground Plane Length

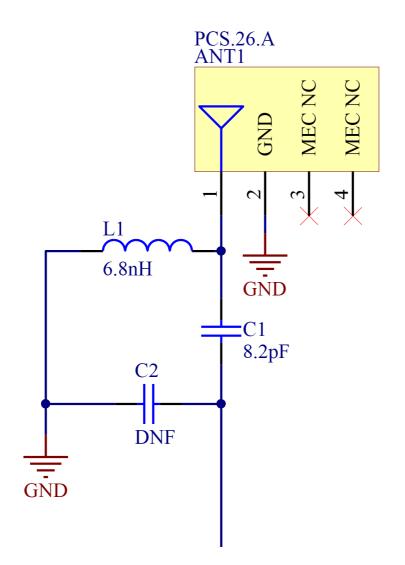


Ground Plane Length 160mm



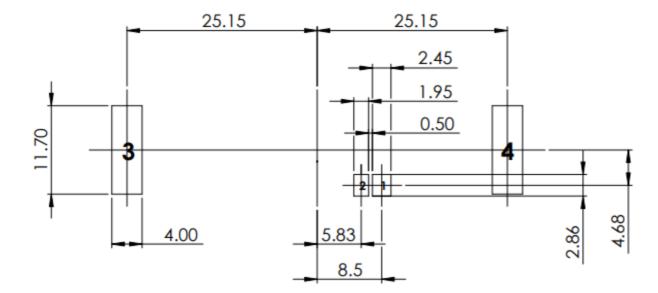
6.8 Evaluation Board Matching Circuit

A matching component (L1) in parallel with the PCS.26.A is required for the antenna to have optimal performance on the evaluation board, located outside of the ground plane in the space specified in the above images. Additional matching components may be necessary for your device, so we recommend incorporating extra component footprints, forming a "pi" network, between the cellular module and the edge of the ground plane.



Designator	Туре	Value	Description
L1	Inductor	6.8nH	TDK: MLK1005S Series
C1	Capacitor	8.2pF	Murata:GRM1555 Series
C2	Capacitor	DNF	

6.9 Footprint

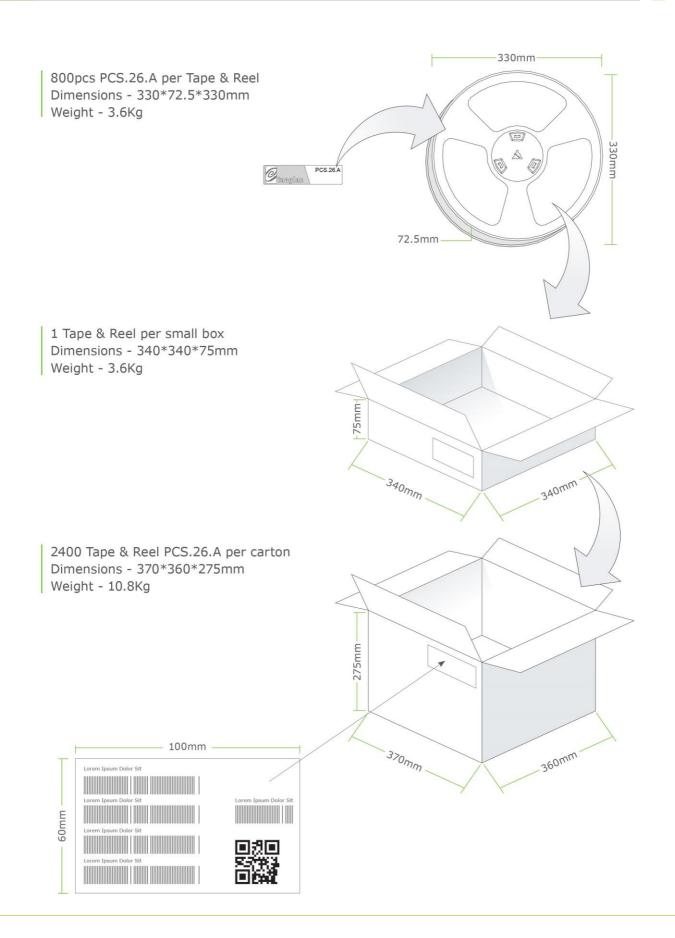


PCB FOOTPRINT

PIN:	DESCRIPTION:
1	Feed (50 ohm)
2	Ground
3,4	NC



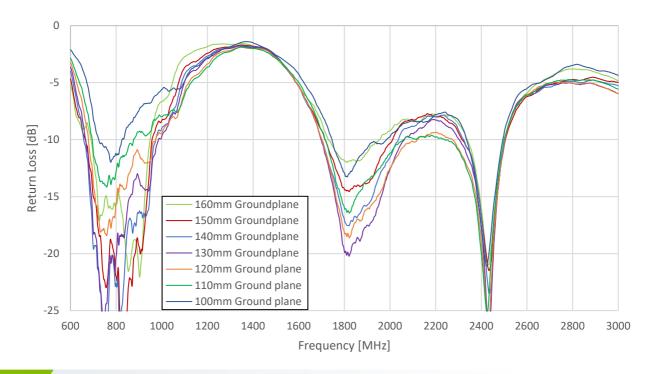
7. Packaging



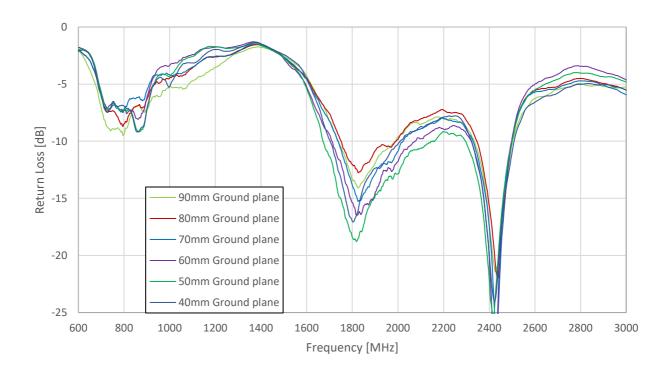


8. Application Note

8.1 Return Loss

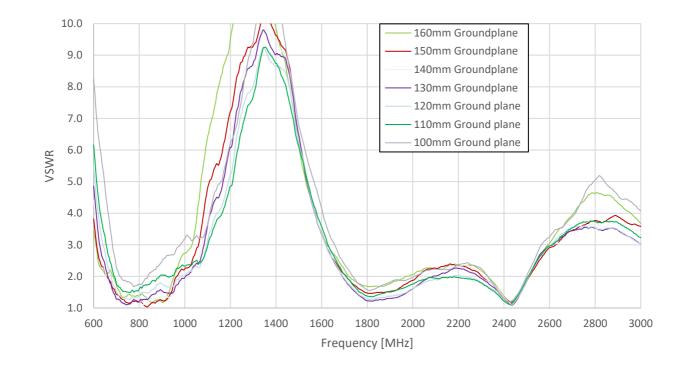


8.2 Return Loss



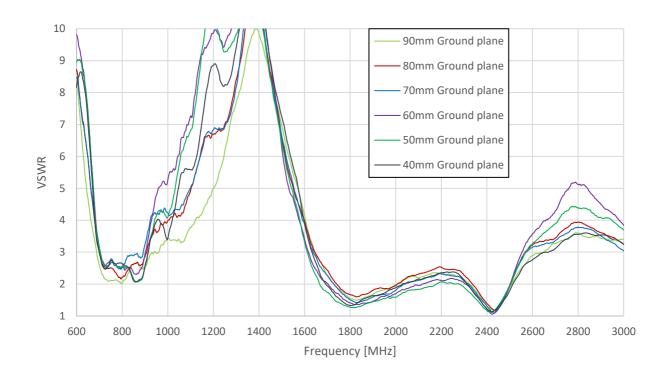




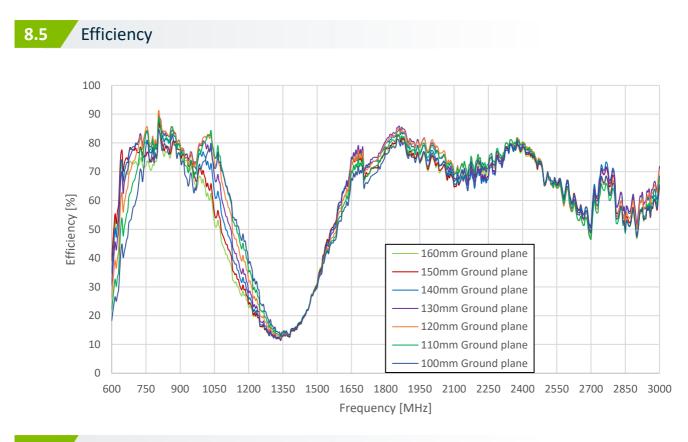




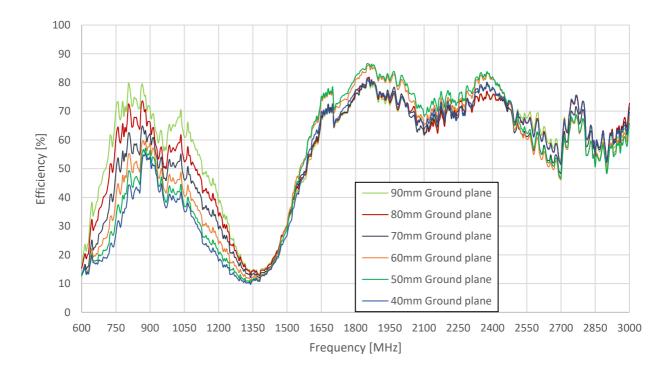
VSWR



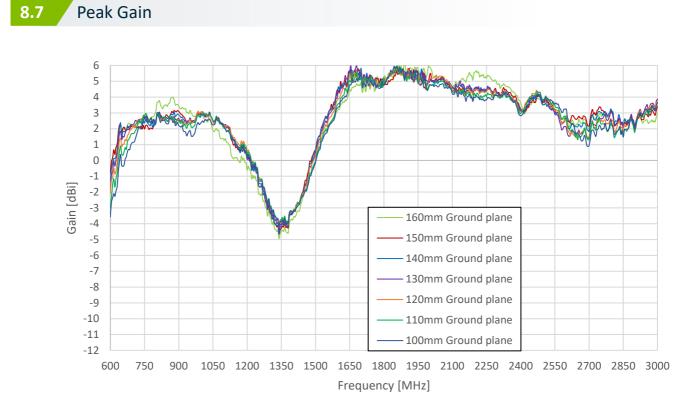




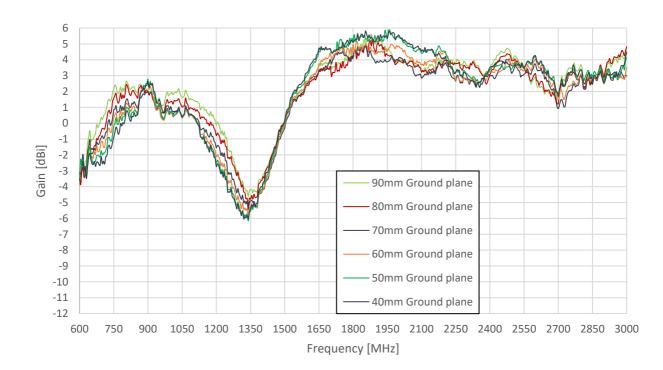






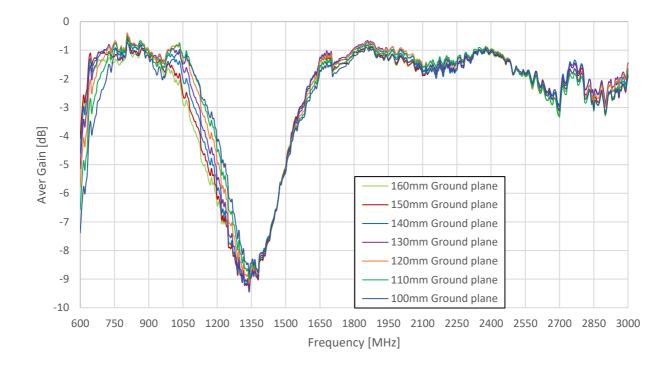




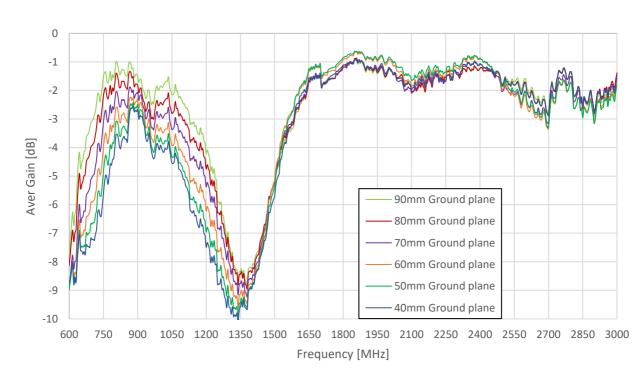




8.9 Average Gain









Changelog for the d	atasheet
SPE-18-8-100 – PCS	.26.A
Revision: E (Current	Version)
Date:	2022-04-26
Changes:	Updated 3D Radiation Patterns
Changes Made by:	Gary West

Previous Revisions

Revision: D	
Date:	2021-10-07
Changes:	Updated datasheet template, addition of intergration guide, addition of application note & added MSL to spec table
Changes Made by:	Gary West

	Revision: C	
	Date:	
	Changes:	
L		
	Changes Made by:	AW

Revision: B	
Date:	2018-11-19
Changes:	Amended EVB size
Changes Made by:	Jack Conroy

Revision: A (First Release)	
Date:	2018-09-11
Changes:	First Release
Changes Made by:	AW





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